

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abbott, et al

Art Unit: 2826

Application No.: 09/525,105

Examiner: Williams, A.

Filed: 03/14/00

Docket: TI-28098

For:

GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR
DEVICES AND METHOD OF FABRICATION

AMENDMENT 37 CFR 1.116

June 13, 2002

Assistant Commissioner
for Patents
Washington, D.C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. 1.8(A)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First
Class Mail bearing sufficient postage in an envelope addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231 on June 13, 2002

Sue Gleason June 13, 2002
Sue Gleason

Sir:

Responsive to the Office Action of April 17, 2002, favorable reconsideration and allowance of the application are respectfully requested.

The rejection of claim 1 as unpatentable over Ito et al is respectfully traversed, since the reference fails to disclose or suggest applicants' invention. Contrary to the Examiner's comment, there is NO disclosure in Ito relating to any gold layer on elements 82b and 83b. The Examiner appears to be mistaken. The rejection is therefore improper and should be withdrawn.

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If the Examiner insists that such a disclosure appears in the reference, please indicate column and line numbers where it can be found.

The rejection of claims 2 - 13 and 15 as unpatentable over Abbott in view of Akino et al and Ito et al is respectfully traversed, since the references fail to disclose or suggest applicant's invention. Since there is no disclosure or suggestion of any gold layer on Ito parts 82b and 83b, the rejection is clearly improper and should be withdrawn.

Applicants now believe the application is in condition for allowance.

Respectfully submitted,



Gary C. Honeycutt
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June 13, 2002

Re: **GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR
DEVICES AND METHOD OF FABRICATION**

Serial No.: 09/525,105
TI's File No.: TI-28098
Our File No.: 50000.2092

Enclosed with this postcard, please find the following:

1. Amendment 37 CFR 1.116; and
2. Postcards.

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<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> AMENDMENT <u>37CFR 1.116</u>
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> EOT
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<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> APPEAL
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<input type="checkbox"/> CONTINUATION APP'N	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE)
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): <u>ABBOTT, ET AL</u>	
RECEIPT DATE & SERIAL NO.: Serial No.: <u>09/525,105</u>	
TITLE OF INVENTION: <u>GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR DEVICES AND METHOD OF FABRICATION</u>	
TI FILE NO.: <u>28098</u>	DEPOSIT ACCT. NO.: <u>20-0668</u>
EXPRESS MAIL RECEIPT NO.: MLD: <u>06/13/02</u> DUE: <u>06/17/02</u> ATTY/SECY: <u>GCH/MSG/KV-</u>	
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G O D W I N G R U B E R

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June 13, 2002

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Assistant Commissioner for Patents
Washington, D.C. 20231-9998

Re: Amendment 37 CFR 1.116

Title: **GOLD SPOT PLATED LEADFRAMES FOR
SEMICONDUCTOR DEVICES AND METHOD OF
FABRICATION**

Appl. No.: 09/525,105

Filing date: 03/14/00

TI File No: TI-28098

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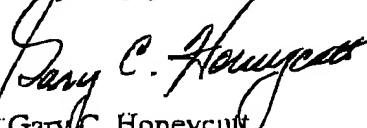
Dear Sir:

Enclosed please find the following items relating to the above-identified patent:

- (1) Amendment 37 CFR 1.116; and
- (3) Postcards.

Please return the date-stamped postcard to our offices at the above address. In the meantime if you have any questions or comments concerning this matter, please call the undersigned at your earliest convenience. Otherwise, please accept the enclosed.

Very truly yours,



Gary C. Honeycutt
Reg. No. 20,250

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Enclosures

cc: James Brady, Texas Instruments Incorporated

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FAX	Number of Pages	5	Date of	6/13/2002
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To	Company	Phone	Fax
Assistant Commissioner for Patents, Washington, D. C. 20231-9998			703-308-7722/7724

From Gary C. Honeycutt (214) 939-8651

Client/Matter Number 50000.2092

Comments

Re: Appln. No.: 09/525,105

**GOLD SPOT PLATED LEADFRAMES FOR SEMICONDUCTOR DEVICES AND
METHOD OF FABRICATION**

Please see the attached Amendment 37 CFR 1.116, and copies of post card attachments. The hard copy of the document has been sent to you via today's first class mail, along with pertinent post cards.

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